

ABSTRACT OF THE DISCLOSURE

An adapter for a surface mount device, the adapter including an insulating body having offset first and second surfaces; a pattern of surface mount solder pads formed on the first surface; a pattern of signal carriers communicating between the first and second  
5 surfaces, each of the signal carriers being at least partially exposed in an area between the first and second surfaces and adjacent to the second surface; and a plurality of signal lines electrically coupling one or more of the surface mount solder pads with predetermined ones of the signal carriers.